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(54) Title: AQUEOUS PHOSPHORIC ACID COMPOSITIONS FOR CLEANING SEMICONDUCTOR DEVICES

(57) Abstract: The present invention relates to dilute aqueous solutions containing phosphoric acid and methods for cleaning plasma etch residue from semiconductor substrates including such dilute aqueous solutions. The solution according to the invention may advantageously contain an alkaline compound, one or more other acid compounds, and/or a fluoride-containing compound and may optionally contain additional components such as organic solvents, chelating agents, amines, and/or surfactants.



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